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SiO₂/TiO₂ distributed Bragg reflector near 1.5 μm fabricated by e-beam evaporation

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The authors report on the fabrication and characterization of SiO₂/TiO₂ distributed Bragg reflector (DBR) mirrors operating at the eye safe and optical communication wavelength window, $\lambda = 1.5 \mu\text{m}$. Our experimental results demonstrated that SiO₂/TiO₂ DBR mirrors with reflectivity exceeding 95% at $\lambda = 1.5 \mu\text{m}$ can be achieved using e-beam evaporation in conjunction with postdeposition thermal annealing process in ambient air. It was found that the postdeposition annealing process transformed the crystal structure of the as-deposited Ti_xO_y to TiO₂, leading to a significant reduction in optical absorption. Erbium doped III-nitride semiconductors incorporating DBR mirrors at 1.5 μm emission may open up many novel applications, including infrared emitters, optical amplifiers, and high power infrared lasers. © 2013 American Vacuum Society. [<http://dx.doi.org/10.1116/1.4823705>]

I. INTRODUCTION

The optical loss of silica fibers, caused by Rayleigh scattering and infrared absorption, has a minimum at the spectral region near $\lambda = 1.5 \mu\text{m}$. Coincidentally, the intra-4*f* transition of trivalent Er atoms (Er³⁺) from the first excited to ground state (⁴I_{13/2} → ⁴I_{15/2}) offers the 1.5 μm emission. Hence, erbium doped semiconductors and dielectric materials have many applications in optical communications, ranging from infrared emitters, erbium doped fiber amplifiers (EDFA), to other photonic devices.^{1,2} Many of these device applications would benefit from the development of distributed Bragg reflectors (DBRs) at $\lambda = 1.5 \mu\text{m}$, which are expected to enhance the optical performance of the photonic devices based on Er doped materials. In particular, Er doped III-nitride semiconductors^{3,4} integrated with DBRs at 1.5 μm are promising for realizing chip-scale electrically or optically pumped optoelectronic devices, including erbium doped waveguide amplifiers, infrared emitters, and high power infrared lasers with superior thermal stability.

DBR mirrors generally consist of many periods of two alternating materials with different refractive indices. The layer thickness of each layer is $\sim \lambda/4n$, where λ and n refer to the light wavelength and refractive index at the targeted wavelength, respectively. In this report, we selected SiO₂ and TiO₂ dielectric materials as alternating DBR layers due to their low absorption coefficients at $\lambda = 1.5 \mu\text{m}$ and a large contrast of refractive indices (Δn), which reduce the periods of DBR mirrors needed to achieve the desired reflectivity and a relatively broad stop band.^{5,6} Because of the well-known fact that heated Ti₃O₅ forms TiO₂ with a supply of oxygen, Ti₃O₅ has been widely used as a source material for TiO₂ thin films deposited by ion-assisted deposition or RF sputtering.^{7–10} However, the optical performance of TiO₂ layers is sensitive to the substrate temperature and environmental O₂ pressure used during ion-assisted deposition or RF sputtering deposition.^{7–10} Moreover, ion-assisted

deposition and RF sputtering processes are less compatible with III-nitride optoelectronic device fabrication processes. In the present study, we prepared SiO₂/TiO₂ DBR mirrors via conventional e-beam evaporation using Ti₃O₅ as the source material from which relatively high purity materials could be achieved within the high vacuum deposition environment. To improve the performance of SiO₂/TiO₂ DBR mirrors deposited by e-beam evaporation, we employed a postdeposition thermal annealing process in ambient air. Our experimental results demonstrated that SiO₂/TiO₂ DBR mirrors with reflectivity >95% at $\lambda = 1.5 \mu\text{m}$ can be achieved using e-beam evaporation in conjunction with postdeposition thermal annealing process in ambient air, providing a new and simplified route for the realization of high quality SiO₂/TiO₂ DBR mirrors.

II. EXPERIMENT

SiO₂/TiO₂ DBR mirrors were deposited on Al₂O₃ substrates using an e-beam evaporator (Edwards 306) with SiO₂ (CERAC, 99.99%) and Ti₃O₅ (CERAC, 99.9%) as the source materials with deposition rates of ~ 4 and ~ 2 nm/min, respectively. The deposition rates were monitored by a gold coated quartz crystal. Thermal annealing processes were then performed in ambient air at various annealing temperatures (T_a) and time (t_a) to improve the performance of SiO₂/TiO₂ DBR mirrors. The reflectivity spectra of SiO₂/TiO₂ DBR mirrors were measured at a near-normal incident using a reflectance probe (Stellarnet) and detected using a thermoelectrically cooled IR spectrometer (Bayspec) with a 550 nm thick aluminum thin film deposited on the Al₂O₃ substrate as the reference sample having a reflectivity of $\sim 97\%$ at $\lambda \sim 1.5 \mu\text{m}$.

III. RESULTS AND DISCUSSIONS

A. TiO₂ thin films

To study the effects of the thermal annealing process on the properties of Ti_xO_y thin films, Ti_xO_y layers of 260 nm in thickness were deposited on Al₂O₃ substrates and then

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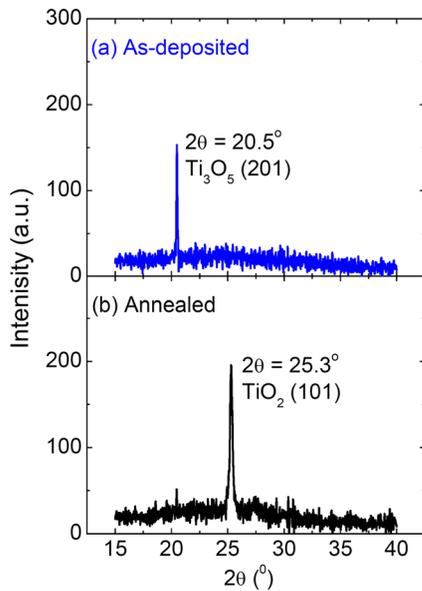


FIG. 1. (Color online) θ - 2θ XRD spectra measured from the (a) as-deposited and (b) annealed ($T_a = 375^\circ\text{C}$ for $t_a = 30$ min in ambient air) $\text{Ti}_x\text{O}_y/\text{Al}_2\text{O}_3$ thin films prepared by e-beam evaporation.

annealed at $T_a = 375^\circ\text{C}$ for $t_a = 30$ min in ambient air. Figure 1 shows θ - 2θ x-ray diffraction (XRD) spectra measured from as-deposited and annealed $\text{Ti}_x\text{O}_y/\text{Al}_2\text{O}_3$ samples. The as-deposited $\text{Ti}_x\text{O}_y/\text{Al}_2\text{O}_3$ sample exhibits a 2θ peak at 20.5° , a reflection peak identified as Ti_3O_5 . In contrast, we observed 2θ peak at 25.3° from the annealed sample, which is identified as a 2θ peak of TiO_2 .^{8,11–13} It appears that the thermal annealing process initiates the crystal structure transformation from Ti_3O_5 to TiO_2 . The as-deposition of Ti_xO_y using a conventional e-beam evaporator occurs in an environment that is deficient in O_2 and hence results in the formation of Ti_3O_5 . Thermal annealing with O_2 transforms Ti_3O_5 to TiO_2 . Figure 2 shows that the change in crystalline property of Ti_xO_y thin films due to the annealing process also altered the reflectance and transmittance spectra of $\text{Ti}_x\text{O}_y/\text{Al}_2\text{O}_3$ samples.^{14,15} It can be seen that the optical

absorption in Ti_xO_y is significantly reduced upon the thermal annealing process.

B. SiO₂/TiO₂ DBR

1. Annealing temperature effect

Five periods of SiO₂/TiO₂ DBR mirrors were deposited on Al₂O₃ substrates with thicknesses of $t_{\text{SiO}_2} = 258$ nm and $t_{\text{TiO}_2} = 206$ nm, respectively, and then followed by thermal annealing in ambient air for $t_a = 60$ min at various temperature, $T_a = 325, 375,$ and 425°C . Figure 3(a) shows the optical microscopy images of the as-deposited and annealed SiO₂/TiO₂ DBR mirrors at different T_a . Notably, as T_a was increased, the image of SiO₂/TiO₂ DBR mirrors changed gradually from opaque black to transparent chartreuse. It was found that, at $T_a \geq 425^\circ\text{C}$, SiO₂/TiO₂ DBR mirrors started to peel off from Al₂O₃ substrates because of the presence of a large strain induced by the difference between the thermal expansion coefficients of SiO₂/TiO₂ DBR mirrors and Al₂O₃ substrates. Also shown in Fig. 3(b) are the reflectivity spectra measured from the as-deposited samples and samples annealed at different temperatures, $T_a = 325$ and 375°C , of 5 periods of SiO₂/TiO₂ DBR mirrors. We observed that thermal annealing changed the reflectivity pattern of SiO₂/TiO₂ DBR mirrors, where the reflectivity at $\lambda = 1.5 \mu\text{m}$ increased from $\sim 51\%$ to $\sim 91\%$ as the temperature was increased up to 375°C .

2. Annealing time dependence

SiO₂/TiO₂ DBR mirrors (2, 5, and 7 periods with $t_{\text{SiO}_2} = 258$ nm and $t_{\text{TiO}_2} = 206$ nm) were annealed at $T_a = 375^\circ\text{C}$ in ambient air for different annealing times (t_a). Figure 4(a) shows the reflectivity spectra measured from as-deposited and annealed samples. The reflectivity spectra were gradually modified with an increase of t_a , where the reflectivity near $\lambda = 1.5 \mu\text{m}$ increased up to 91% for $t_a \geq 60$ min. Figure 4(b) summarizes the infrared reflectivity near $\lambda = 1.5 \mu\text{m}$ as a function of t_a measured for 2, 5, and 7 periods of SiO₂/TiO₂ DBR mirrors. The infrared reflectivity at $\lambda = 1.5 \mu\text{m}$

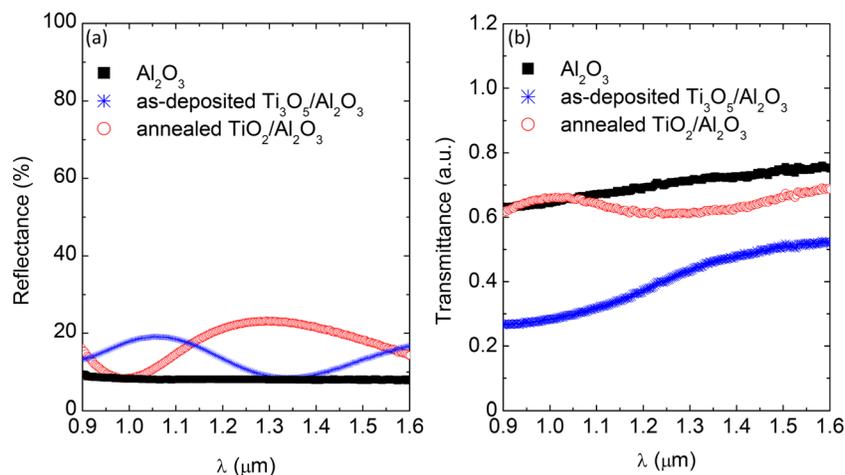


FIG. 2. (Color online) (a) Reflectance and (b) transmittance spectra measured from the as-deposited $\text{Ti}_x\text{O}_y/\text{Al}_2\text{O}_3$ and annealed $\text{TiO}_2/\text{Al}_2\text{O}_3$ samples ($T_a = 375^\circ\text{C}$ for $t_a = 30$ min in ambient air).

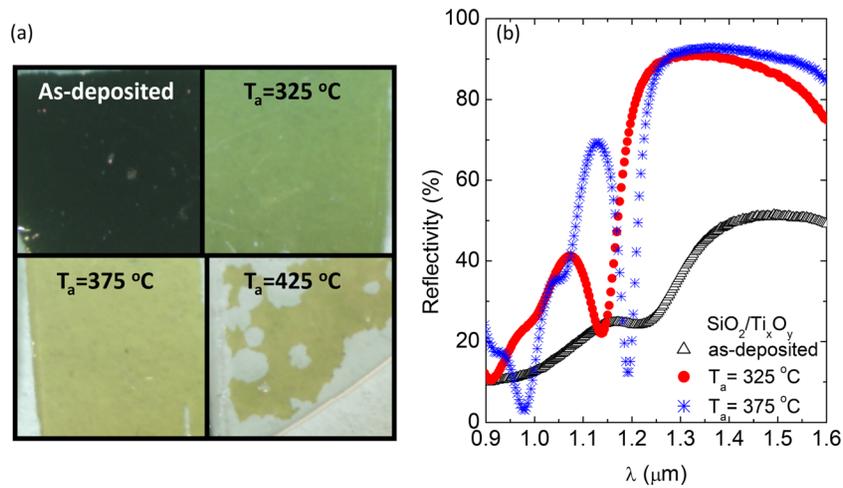


FIG. 3. (Color online) Optical microscopy images of the as-deposited SiO₂/Ti_xO_y and annealed SiO₂/TiO₂ (258 /206 nm) DBR mirrors (5 periods) with T_a = 325, 375, and 425 °C and t_a = 60 min in ambient air. (b) Reflectivity spectra measured from the as-deposited SiO₂/Ti_xO_y and annealed 5 periods of SiO₂/TiO₂ DBR mirrors with T_a = 325 and 375 °C and t_a = 60 min in ambient air.

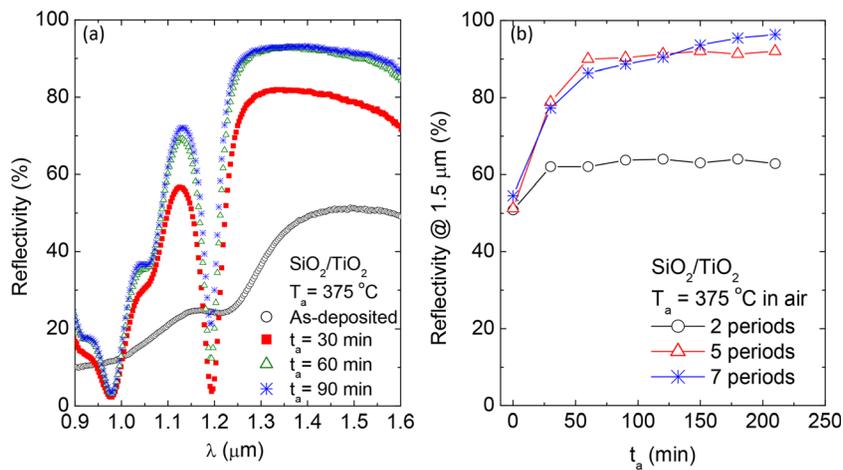


FIG. 4. (Color online) (a) Reflectivity spectra measured from the as-deposited SiO₂/Ti_xO_y and annealed (T_a = 375 °C in ambient air) SiO₂/TiO₂ (258/206 nm) DBR mirrors (5 periods) with different t_a. (b) Reflectivity at λ = 1.5 μm as a function of t_a measured from SiO₂/TiO₂ DBR mirrors with 2, 5, and 7 periods (T_a = 375 °C in ambient air).

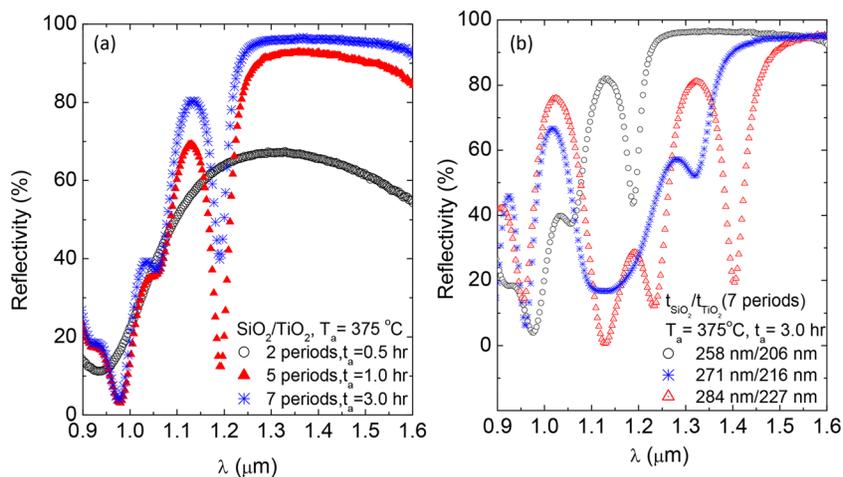


FIG. 5. (Color online) (a) Reflectivity spectra measured from annealed SiO₂/TiO₂ DBR mirrors with thicknesses of t_{SiO₂} = 258 nm and t_{TiO₂} = 206 nm and with 2, 5, and 7 periods annealed at each optimized t_a of 0.5, 1.0, and 3.0 h, respectively. (b) Reflectivity spectra measured from the annealed SiO₂/TiO₂ DBR mirrors (7 periods) at T_a = 375 °C for t_a = 3.0 h with different t_{SiO₂}/t_{TiO₂} thicknesses (258/206 nm, 271/216 nm, and 284/227 nm).

increases with an increase of t_a and then appears to saturate. It was also observed that SiO₂/TiO₂ DBR mirrors with more periods reach a higher reflectivity level but require a longer t_a to reach their maximum reflectivity.

3. Period and thickness dependence

Figure 5(a) shows the reflectivity spectra of the annealed SiO₂/TiO₂ DBR mirrors of 2, 5, and 7 periods with thicknesses of $t_{\text{SiO}_2} = 258$ nm and $t_{\text{TiO}_2} = 206$ nm at each optimized annealing condition. The reflectivity near 1.5 μm increased up to 96% with an increase of the period of the samples. Also shown in Fig. 5(b) are the reflectivity spectra of the annealed samples with varying $t_{\text{SiO}_2}/t_{\text{TiO}_2}$ thickness, 258/206 nm, 271/216 nm, and 284/227 nm, with a nearly constant $t_{\text{SiO}_2}/t_{\text{TiO}_2}$ ratio. It was observed that the stop band of the annealed samples red-shifted with an increase in the layer thickness. The annealed sample with thicknesses of $t_{\text{SiO}_2} = 271$ nm and $t_{\text{TiO}_2} = 216$ nm attains the reflectivity >95% with the stop band covering the full spectral window of the intra-4*f* transition from ⁴I_{13/2} to ⁴I_{15/2} of Er³⁺ ions in III-nitride semiconductors.

IV. SUMMARY AND CONCLUSIONS

In summary, we have fabricated SiO₂/TiO₂ DBR mirrors by e-beam evaporation in conjunction with a postdeposition thermal annealing process. The reflectivity spectra of SiO₂/TiO₂ DBR mirrors near 1.5 μm can be controlled by the thermal annealing conditions as well as by the period and layer thickness of the DBRs, where we are able to achieve DBR mirrors with a reflectivity >95% near $\lambda = 1.5$ μm. Erbium doped semiconductors integrated with SiO₂/TiO₂ DBR mirrors will open up novel applications including infrared

emitters, optical amplifiers, and high power lasers operating at the technologically important and eye safe 1.5 μm spectral region.

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